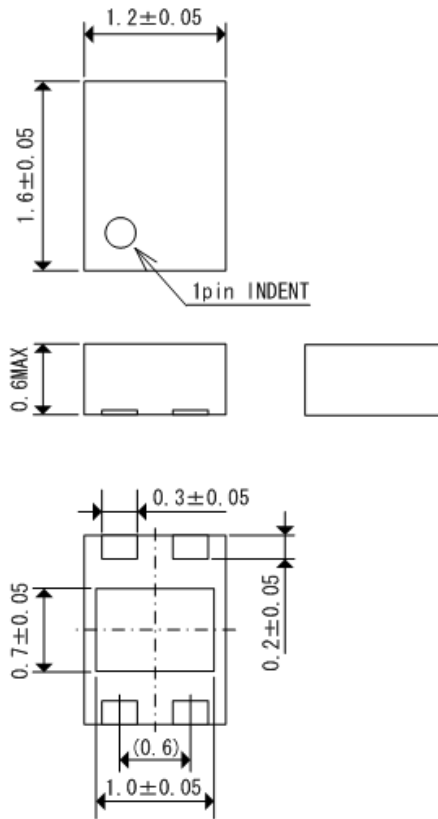


Packaging Information / Reference Pattern Layout Dimensions

● USP-4

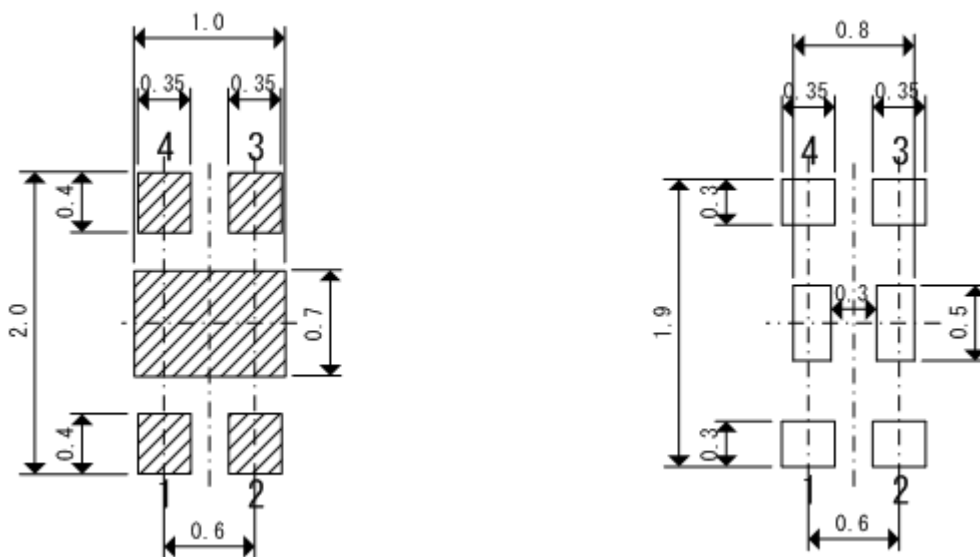
Unit: mm

■ Packaging Information



■ Reference Pattern Layout Dimension

Note : reference metal mask design

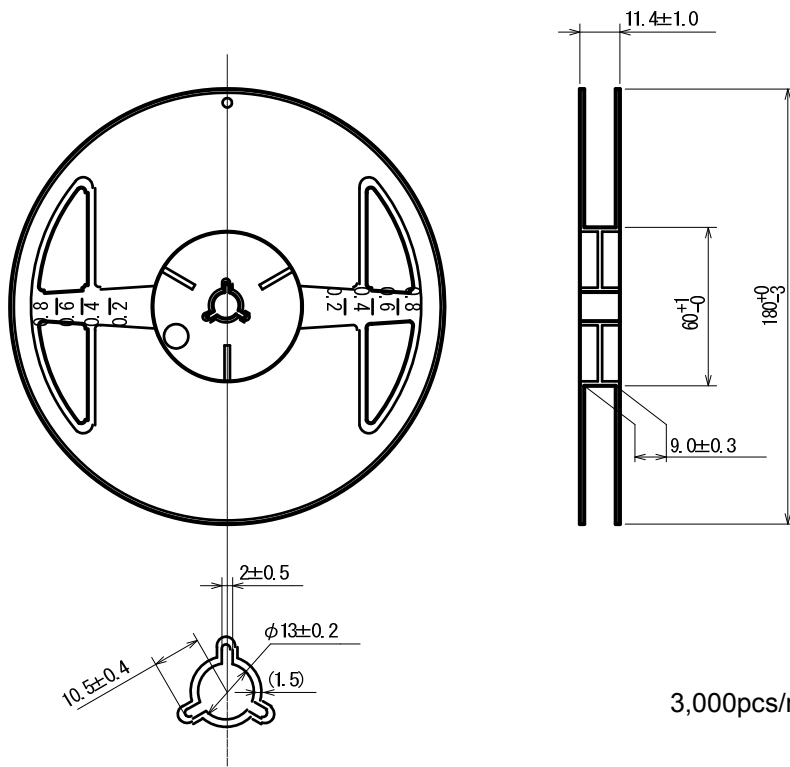


テーピング仕様 / Taping Specifications

USP-4

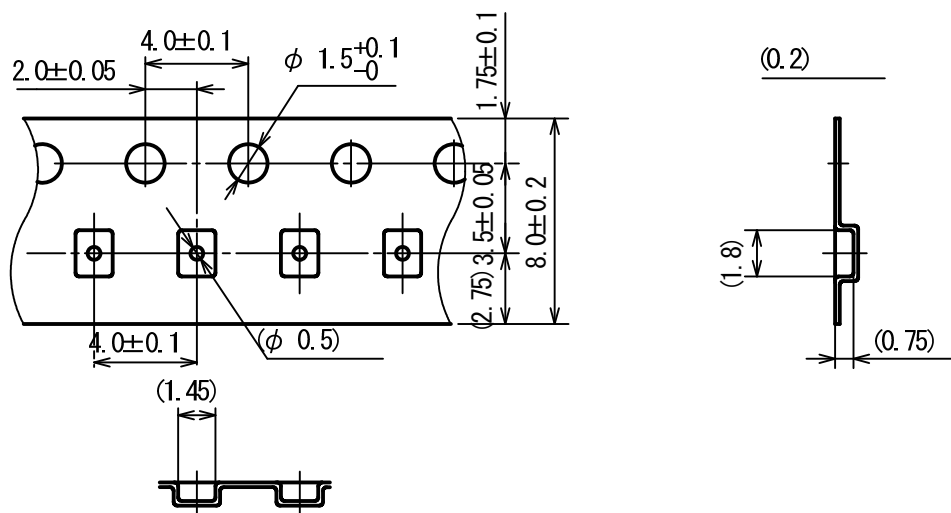
●リール/Reel

Unit: mm

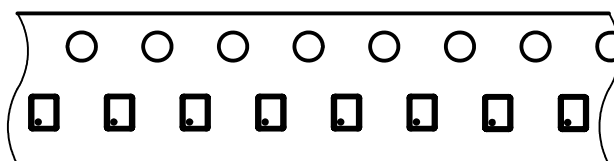


3,000pcs/reel

●テーピング仕様/Taping Specifications



direction of feed



R Type : [Device orientation : Right]

Standard feed

●USP-4 Power Dissipation

Power dissipation data for the USP-4 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

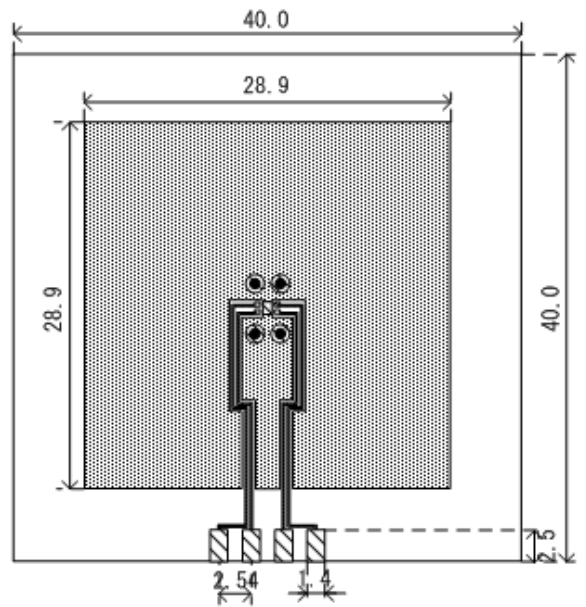
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

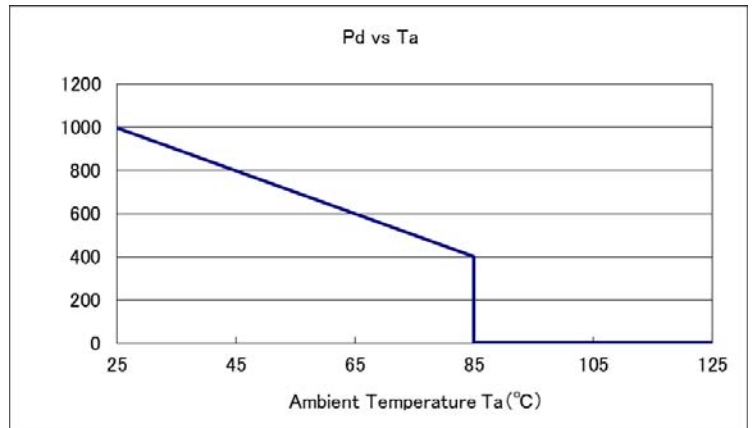


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature (85°C)

Board Mount (T_{jmax}=125°C)

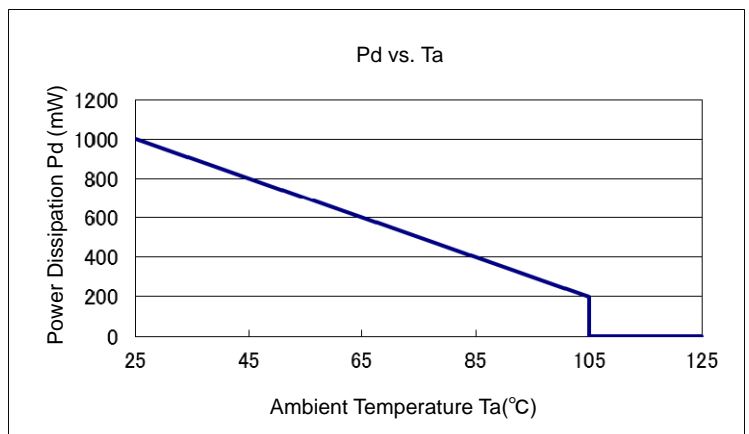
| Ambient Temperature (°C) | Power Dissipation Pd (mW) | Thermal Resistance (°C/W) |
|--------------------------|---------------------------|---------------------------|
| 25 | 1000 | 100.00 |
| 85 | 400 | |



3. Power Dissipation vs. Ambient Temperature (105°C)

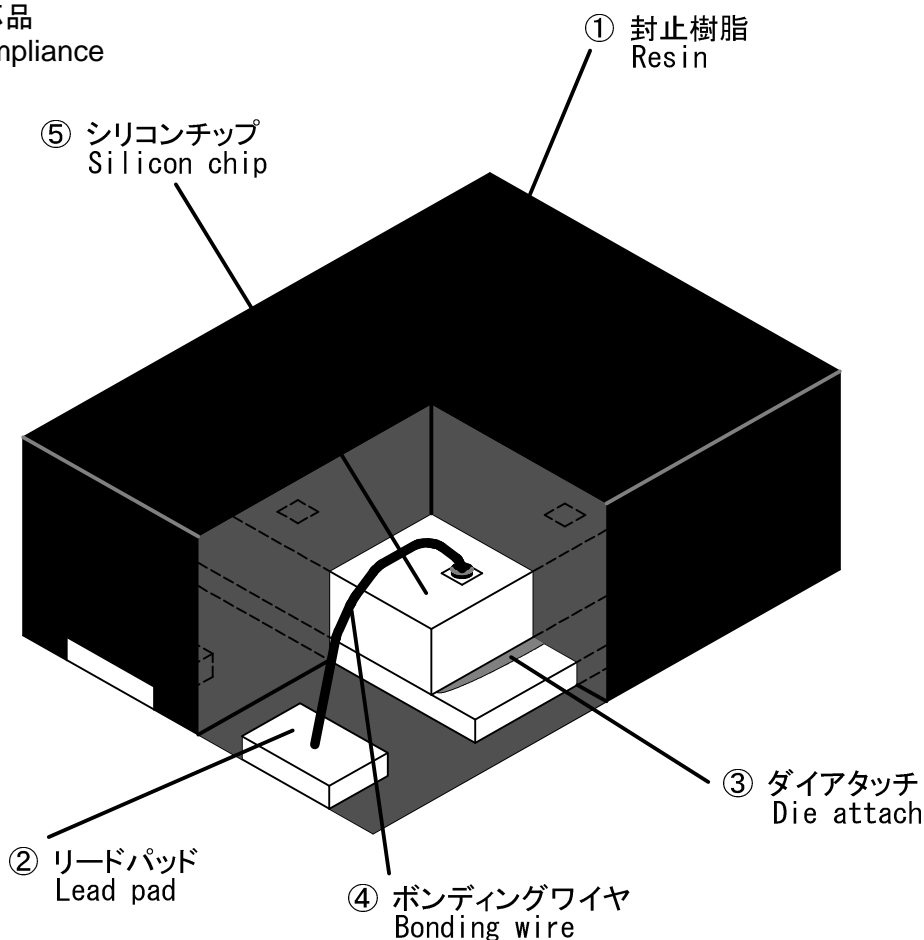
Board Mount (T_{jmax}=125°C)

| Ambient Temperature (°C) | Power Dissipation Pd (mW) | Thermal Resistance (°C/W) |
|--------------------------|---------------------------|---------------------------|
| 25 | 1000 | 100.00 |
| 85 | 200 | |



USP-4 構造図
USP-4 Perspective

RoHS対応品
RoHS Compliance



| 項目 item | 材料 material | 備考 Note |
|-----------------------------|-----------------------|--|
| ① 封止樹脂 Resin | エポキシ樹脂 Epoxy resin | 難燃グレード/Flammability rating UL94V-0 |
| ② リードパッド Lead pad | ニッケル Nickel | |
| 端子処理 Outer pad plating | Auメッキ Gold plating | 端子側面は除く Except the side of the terminals. |
| ③ ダイアタッチ Die attach | エポキシ Epoxy | |
| ④ ボンディングワイヤ Bonding wire | Au | |
| ⑤ シリコンチップ Silicon chip | Si | |

| | |
|-----------------|-----------------------|
| 捺印表示 Marking | レーザー Laser marking |
|-----------------|-----------------------|